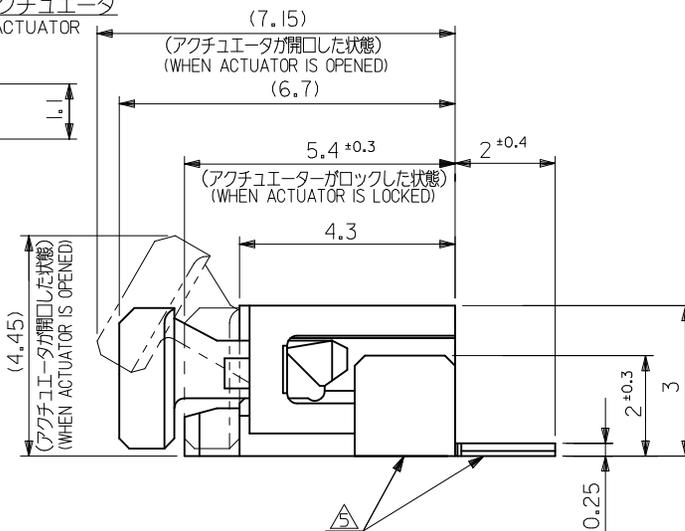
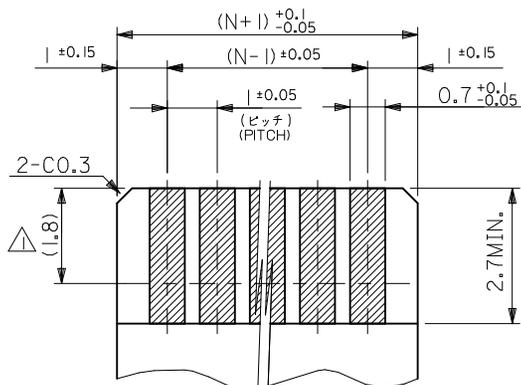


SECT. D-D

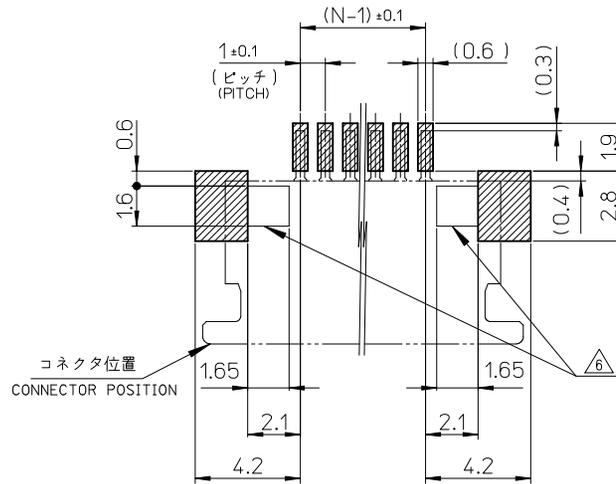


35	31.2	29	52271-3069	30
34	30.2	28	52271-2969	29
33	29.2	27	52271-2869	28
32	28.2	26	52271-2769	27
31	27.2	25	52271-2669	26
30	26.2	24	52271-2569	25
29	25.2	23	52271-2469	24
28	24.2	22	52271-2369	23
27	23.2	21	52271-2269	22
26	22.2	20	52271-2169	21
25	21.2	19	52271-2069	20
24	20.2	18	52271-1969	19
23	19.2	17	52271-1869	18
22	18.2	16	52271-1769	17
21	17.2	15	52271-1669	16
20	16.2	14	52271-1569	15
19	15.2	13	52271-1469	14
18	14.2	12	52271-1369	13
17	13.2	11	52271-1269	12
16	12.2	10	52271-1169	11
15	11.2	9	52271-1069	10
14	10.2	8	52271-0969	9
13	9.2	7	52271-0869	8
12	8.2	6	52271-0769	7
11	7.2	5	52271-0669	6
10	6.2	4	52271-0569	5
9	5.2	3	52271-0469	4
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUITS
52271-**-29			CONNECTOR SERIES NO.	

REVISED EC NO.: J2012-1390 DRWN:KNAGUMO 2012/05/10 CHKD:KAKAHASHI 2012/05/10 APPR:KMORIKAWA 2012/05/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	TITLE <b>1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-</b> <b>molex</b> DOCUMENT NO. SD-52271-038 SHEET NO. 1 OF 2
	10 UNDER ±0.2		MM ONLY	10:1	METRIC	
	10 OVER 30 UNDER ±0.25		DRAWN BY	DATE		
	30 OVER ±0.3		M.UMEDA	2005/03/08		
DESCRIPTION REV	ANGULAR ±3 °		CHECKED BY	DATE		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		K.TOYODA	2005/03/08		
			APPROVED BY	DATE		
			N.UKITA	2005/03/08		
		MATERIAL NO.	SEE CHART			
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



(仕上り厚さ: 0.3±0.05)  
(THICKNESS: 0.3±0.05)  
適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(SCALE 10:1)



参考基板レイアウト  
RECOMMENDED PCB  
PATTERN DIMENSIONS(REF.)  
(SCALE 5:1)

注記 NOTES

- △1 接点部までの嵌合長さ。  
LENGTH TO CONTACT POINT.
- 2. 使用材料 MATERIAL
  - ハウジング : 46 NYLON, UL94V-0  
HOUSING
  - アクチュエータ : PPS, UL94V-0  
ACTUATOR
  - ターミナル : リン青銅 (t=0.25)  
TERMINAL PHOSPHOR BRONZE (t=0.25)
  - メッキ : 接点部:金メッキ : 0.1 MICROMETER MIN.  
CONTACT PORTION : GOLD PLATING : 0.1 MICROMETER MIN.  
半田付部:錫メッキ : 1.0 MICROMETER MIN.  
SOLDERING PORTION : TIN PLATING : 1.0 MICROMETER MIN.  
下地:ニッケルメッキ : 1.0 MICROMETER MIN.  
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
  - 金具 : 銅合金 (t=0.25)  
FITTING NAIL CAPPER ALLOY (t=0.25)
  - メッキ:錫メッキ : 1.0 MICROMETER MIN.  
PLATING : TIN PLATING : 1.0 MICROMETER MIN.
  - 下地:ニッケルメッキ : 1.0 MICROMETER MIN.  
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.

- △3 パターンはくり止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING  
OF P.C.B. PATTERN.
- 4. エンボステーブ梱包時は、アクチュエータがロックした状態とする。  
IN THE PACKAGE, ACTUATOR OF PART NO.54550-\*\*\*29 SHOULD BE LOCKED.
- △5 テール及び金具の平坦度は、0.15以下とする。  
TAIL AND NAIL COPLANRITY TO BE 0.15 MAXIMUM.
- △6 パターン書き込み禁止エリア  
NO FOOT PRINT AREA.

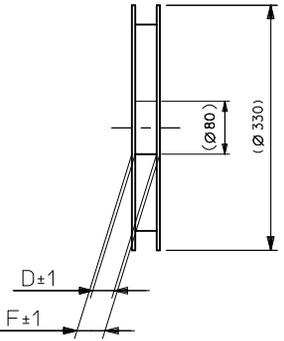
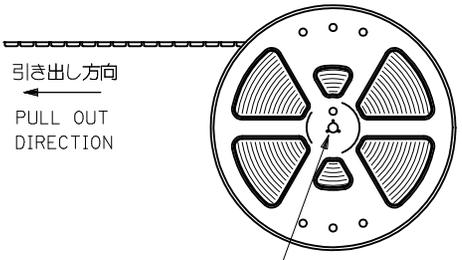
FPC について :

打抜き方向は、導体側から補強板側を推奨致します。  
補強フィルム材質は、ポリイミドを推奨致します。  
接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC :

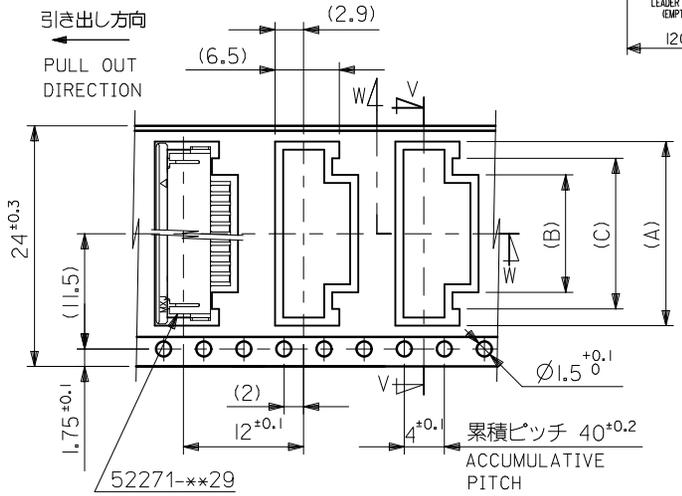
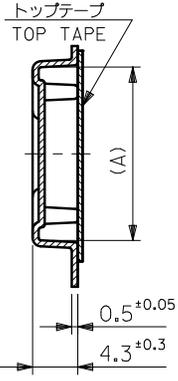
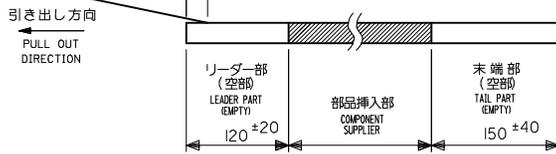
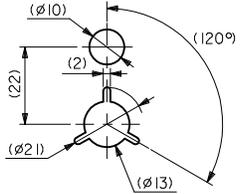
RECOMMENDED PUNCHER DIRECTION :  
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO. J2012-1390 DRWN:KNAGUMO 2012/05/10 CHKD:KAKAHASHI 2012/05/10 APP:KMORIKAWA 2012/05/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08		
ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-52271-038	SHEET NO. 2 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

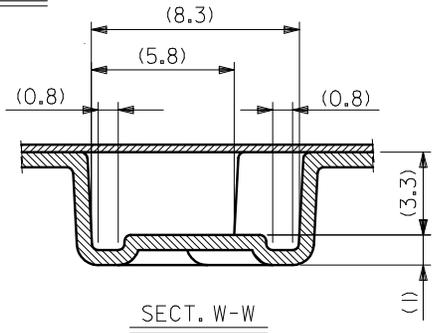


NOTES

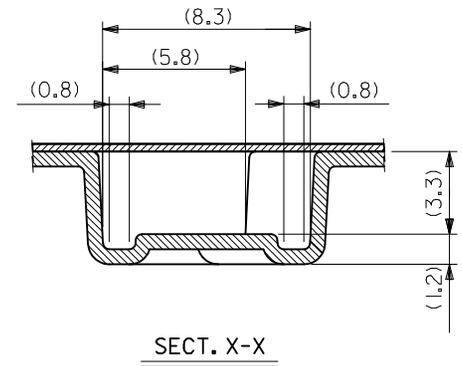
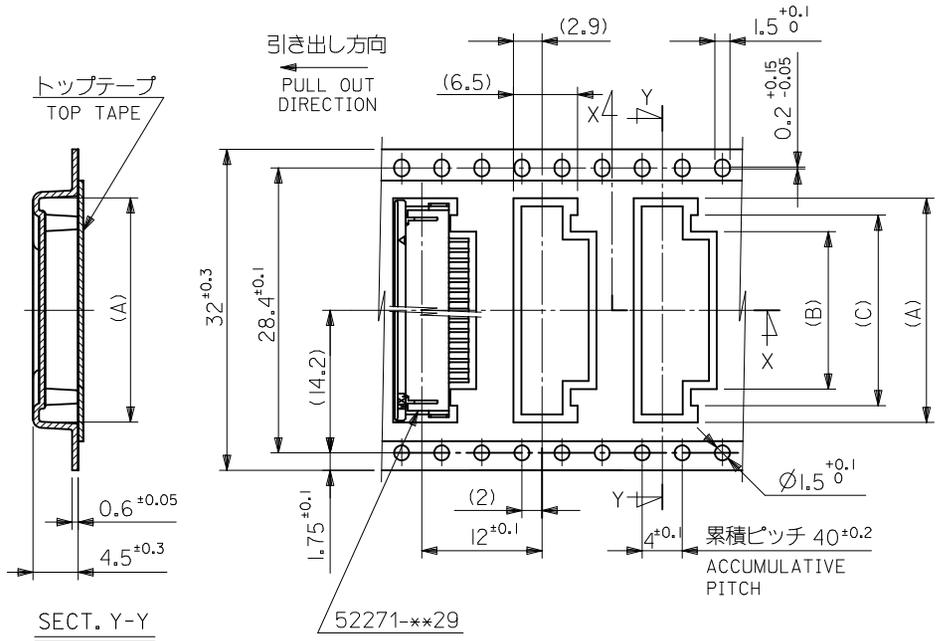
- 製品番号 52271-\*\*29 の梱包状態はアクチュエータがロックした状態とする。詳細寸法については 図面 SD-52271-038 を参照下さい。  
IN THE PACKAGE, AUTUATOR OF PART NO. 52271-\*\*29 SHOULD BE LOCKED RE DETAILED DIMENSIONS, SEE SD-52271-038.
- 梱包数量：1000個/リール  
NUMBER OF CONNECTORS：1000 PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープ リーダー部 TOP TAPE LEADER PART 175 ±25  
トップテープ 未接層部 TOP TAPE NON-BONDED PART 25 ±5
- カバーテープの剥離強度については、IEC60286-3に準拠  
COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE)：ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOPTAPE)：PET, PE, PEF  
リール (REEL)：ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.



24	29.4	25.4	15	11.4	18.3	52271-1169	11
			14	10.4	17.3	52271-1069	10
			12	8.4	15.3	52271-0869	8
			11	7.4	14.3	52271-0769	7
			10	6.4	13.3	52271-0669	6
			9	5.4	12.3	52271-0569	5
			8	4.4	11.3	52271-0469	4
			キャリアテープ幅 CARRIER TAPE WIDTH			F	D

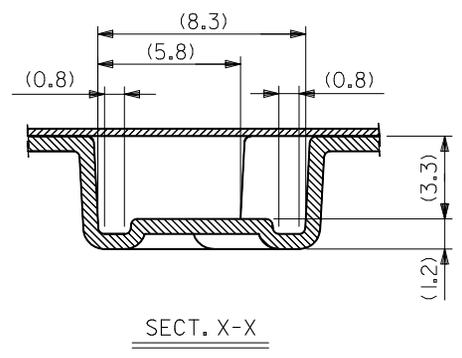
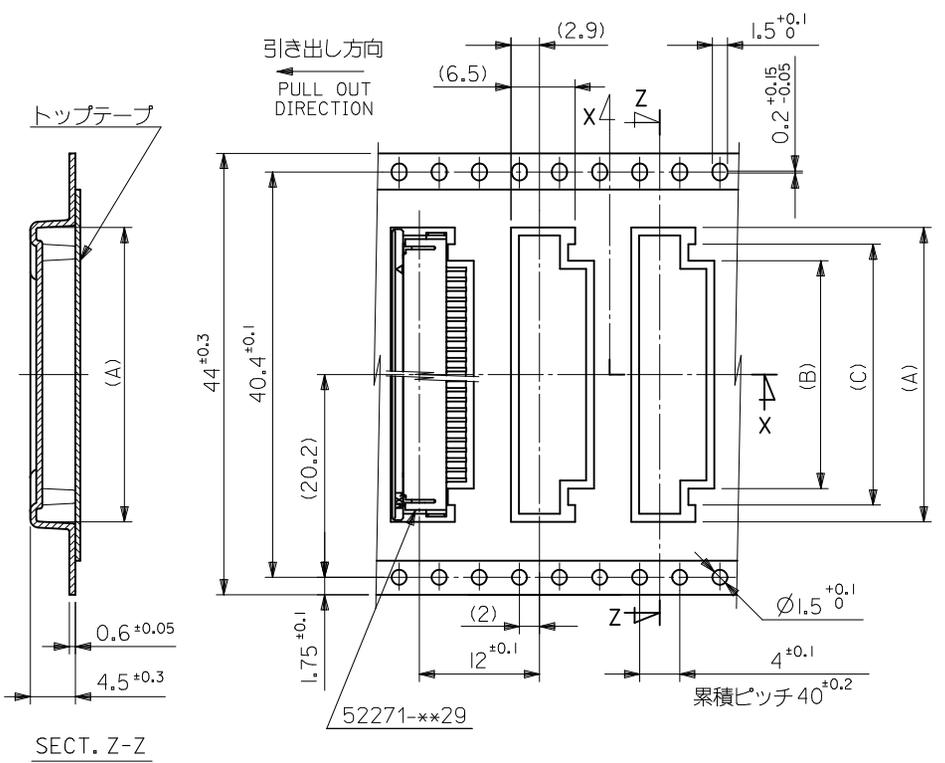


REVISED EC NO: J2010-2474 DRWN: YUHASHIGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORI KAWA 2010/06/09	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		52271-**69		MODEL NO.	
		10 UNDER ±0.2		DRAWN BY DATE M. UEDA 2005/03/08		SCALE ---		DESIGN UNITS METRIC	
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOYODA 2005/03/08		TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-		THIRD ANGLE PROJECTION	
		30 OVER ±0.3		APPROVED BY DATE N. UKITA 2005/03/08		MATERIAL NO.		DOCUMENT NO.	
		ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SEE TABLE		SD-52271-039	



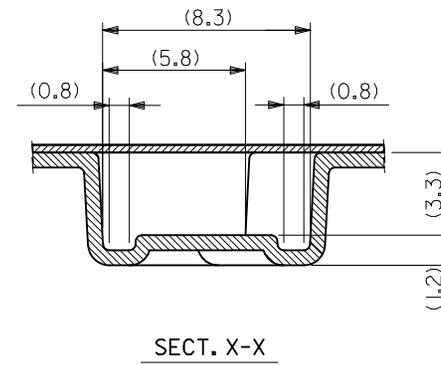
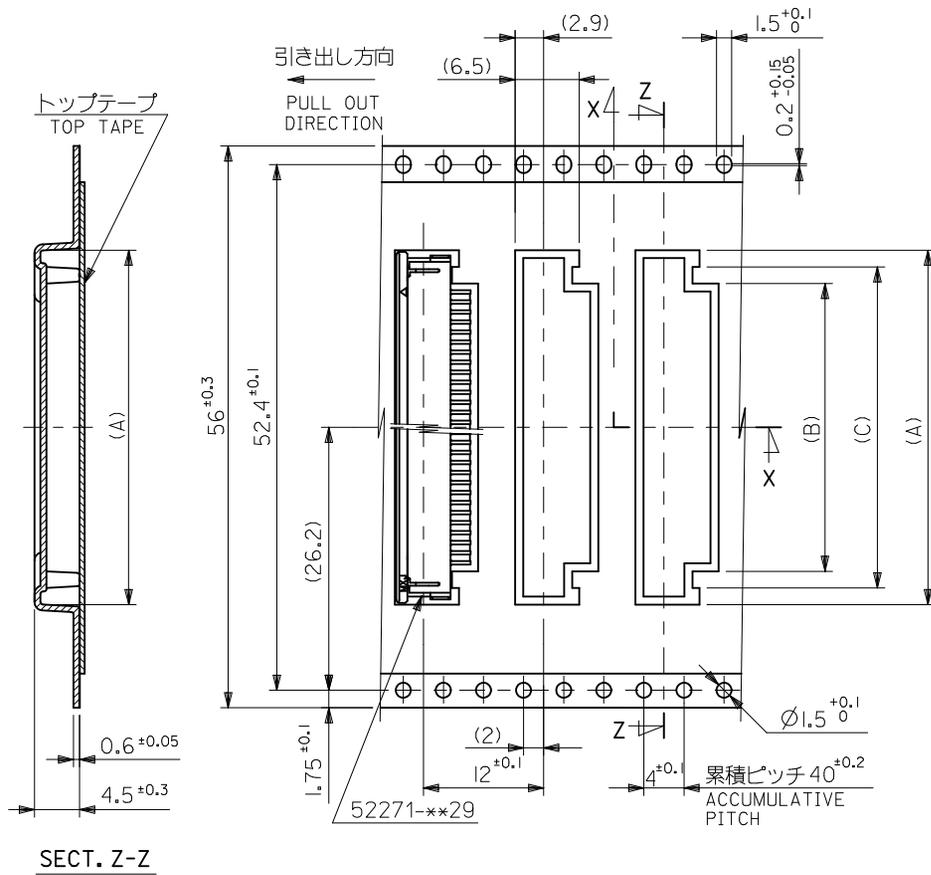
32	37.4	33.4	20	16.4	23.35	52271-1669	16		
			19	15.4	22.35	52271-1569	15		
			18	14.4	21.35	52271-1469	14		
			17	13.4	20.35	52271-1369	13		
			16	12.4	19.35	52271-1269	12		
キャリアテープ幅 CARRIER TAPE WIDTH			F	D	(C)	(B)	(A)	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHKD: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. UMEDA	DATE 2005/03/08	TITLE EMBOSSSED TAPE PACKAGE FOR 52271-**-29 -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2005/03/08	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2005/03/08	DOCUMENT NO. SD-52271-039				
		ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 4		



44	49.4	45.4	31	27.4	34.35	52271-2769	27		
			29	25.4	32.35	52271-2569	25		
			28	24.4	31.35	52271-2469	24		
			26	22.4	29.35	52271-2269	22		
			25	21.4	28.35	52271-2169	21		
			24	20.4	27.35	52271-2069	20		
			23	19.4	26.35	52271-1969	19		
			22	18.4	25.35	52271-1869	18		
			21	17.4	24.35	52271-1769	17		
キャリアテープ幅			F	D	(C)	(B)	(A)	MATERIAL NO.	極数

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CHK'D: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08	DOCUMENT NO. SD-52271-039				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 3 OF 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



SECT. Z-Z

SECT. X-X

56	61.4	57.4	34	30.4	37.35	52271-3069	30
			32	28.4	35.35	52271-2869	28
キャリアテープ幅 CARRIER TAPE WIDTH			F	D	(C)	(B)	(A)
						MATERIAL NO.	種数 CKT.

REVISED EC NO: J2010-2474 DRWN: YUHASEGAWA 2010/06/08 CH'KD: K. TOYODA 2010/06/08 APPR: KMORIKAWA 2010/06/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE EMBOSSD TAPE PACKAGE FOR 52271-**29 -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K.TOYODA	DATE 2005/03/08	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N.UKITA	DATE 2005/03/08	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52271-039	SHEET NO. 4 OF 4
	ANGULAR ±3 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

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